

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
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WAI MAN WONG	02/26/2019
CHIU KEUNG LOONG	02/26/2019
RECEIVING PARTY DATA	
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State/Country:	HONG KONG
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	18119054
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DATE SIGNED:	01/31/2024
Total Attachments: 3	
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source=403C1_Assignment_Inventors#page3.tif	

ASSIGNMENT

WHEREAS, we,

Name	Address	
Wai Man WONG	5/F, Chai Wan Industrial Centre, 20 Lee Chung Street, Chai Wan, Hong Kong	and
Chiu Keung LOONG	5/F, Chai Wan Industrial Centre, 20 Lee Chung Street, Chai Wan, Hong Kong	

(hereinafter referred to as ASSIGNORS), having mailing addresses as listed above, are the joint inventors of an invention entitled "A CONTROL ASSEMBLY FOR USE IN OPERATION OF AN ELECTRIC DEVICE" ("the Invention"), for which an application for United States letters patent was filed on November 5, 2018, and assigned Application No. 16/180,922; which claims priority to Hong Kong Short Term Patent Application No. 17111877.6, filed November 15, 2017; and

WHEREAS, DEFOND COMPONENTS LIMITED, a Hong Kong company, having its principal place of business in Chai Wan, Hong Kong, is desirous of acquiring an interest therein;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, ASSIGNORS hereby sell, assign and transfer unto said ASSIGNEES, the entire right, title and interest in and to said invention, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions including any extensions or adjustments in term thereof and in any and all foreign countries, and in any and all divisions, reissues and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEES and to claim priority rights deriving from said Hong Kong Short Term Patent Application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, and including the right to sue and collect damages for past and present infringement of said letters patent; said invention, application and all letters patent on said invention to be held


and enjoyed by ASSIGNEES and their successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNORS had this assignment, transfer and sale not been made. ASSIGNORS hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEES. ASSIGNORS agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefor.

Further, we hereby covenant and agree to and with DEFOND COMPONENTS LIMITED, and its successors and assigns, at the time of execution and delivery of these presents, that we are the sole and lawful owners of the entire right, title, and interest in and to the invention and the above-identified patent application, and that the same are unencumbered, and that we have good and full right and lawful authority to sell and convey the same in the manner herein set forth.

Further, we agree that we will communicate to DEFOND COMPONENTS LIMITED, or its representatives, any facts known to us respecting the invention, and testify in any legal proceedings, sign all lawful papers, execute all subsequent, related provisional, U.S. non-provisional, divisional, continuation, reissue, substitution, and extension applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to DEFOND COMPONENTS LIMITED, make all rightful oaths, and generally do everything possible to aid DEFOND COMPONENTS LIMITED, and its successors and assigns, to obtain and enforce proper protection for the invention in the United States and in any and all foreign countries.

Assignees' counsel is authorized to insert the official filing date and application number information when it becomes available.

26 Feb. 2019
Date


Wai Man WONG (Assignor)

I certify that I know or have satisfactory evidence that Wai Man WONG signed this instrument of his/her own free will, as a voluntary act for the uses and purposes mentioned in the instrument.

Date 26 Feb 2019

Signed at Hong Kong

SAMSON KWAN
(Name of Witness)


(Signature of Witness)

Date 26 Feb 2019

Chiu Keung LOONG

(Assignor)

I certify that I know or have satisfactory evidence that Chiu Keung LOONG signed this instrument of his/her own free will, as a voluntary act for the uses and purposes mentioned in the instrument.

Date 26 Feb 2019

Signed at Hong Kong

SAMSON KWAN
(Name of Witness)


(Signature of Witness)

Defond Components Limited

Date 13 MAR 2019


(Signatory Signature) (Assignee)

RICHARD DR (CEO)
(Assignee Signatory Name, Title)